

UNITED STATES
SECURITIES AND EXCHANGE COMMISSION
WASHINGTON, DC 20549

FORM 8-K

CURRENT REPORT
Pursuant to Section 13 or 15(d) of the Securities Exchange Act of 1934

Date of Report (Date of earliest event reported): July 9, 2025

SmartKem, Inc.

(Exact name of registrant as specified in its charter)

Delaware
(State or other jurisdiction
of incorporation)

001-42115
(Commission
File Number)

85-1083654
(IRS Employer
Identification No.)

**Manchester Technology Center, Hexagon Tower
Delaunays Road, Blackley
Manchester, M9 8GQ U.K.**
(Address of principal executive offices, including zip code)

011-44-161-721-1514
(Registrant's telephone number, including area code)

N/A
(Former name or former address, if changed since last report)

Check the appropriate box below if the Form 8-K filing is intended to simultaneously satisfy the filing obligation of the registrant under any of the following provisions:

- ☐ Written communications pursuant to Rule 425 under the Securities Act (17 CFR 230.425)
- ☐ Soliciting material pursuant to Rule 14a-12 under the Exchange Act (17 CFR 240.14a-12)
- ☐ Pre-commencement communications pursuant to Rule 14d-2(b) under the Exchange Act (17 CFR 240.14d-2(b))
- ☐ Pre-commencement communications pursuant to Rule 13e-4(c) under the Exchange Act (17 CFR 240.13e-4(c))

Securities registered pursuant to Section 12(b) of the Act:

Title of each class	Trading Symbol(s)	Name of exchange on which registered
Common Stock, par value \$0.0001 per share	SMTK	The Nasdaq Stock Market LLC

Indicate by check mark whether the registrant is an emerging growth company as defined in Rule 405 of the Securities Act of 1933 (§230.405 of this chapter) or Rule 12b - 2 of the Securities Exchange Act of 1934 (§240.12b - 2 of this chapter).

Emerging growth company ☒

If an emerging growth company, indicate by check mark if the registrant has elected not to use the extended transition period for complying with any new or revised financial accounting standards provided pursuant to Section 13(a) of the Exchange Act. ☐

Item 8.01 Other Events.

On July 9, 2025, SmartKem, Inc. issued a press release announcing that it has signed a preliminary joint development agreement with Manz Asia. A copy of the press release is filed as Exhibit 99.1 hereto and is incorporated by reference herein.

Item 9.01 Financial Statements and Exhibits.

(d) The following exhibit is furnished with this report:

Exhibit No.	Description
99.1	Press Release, dated July 9, 2025
104	Cover Page Interactive Data File (embedded within the Inline XBRL document)

Signature

Pursuant to the requirements of the Securities Exchange Act of 1934, the registrant has duly caused this report to be signed on its behalf by the undersigned hereunto duly authorized.

SMARTKEM, INC.

Dated: July 9, 2025

By: /s/ Barbra C. Keck
Barbra C. Keck
Chief Financial Officer



PRESS RELEASE

Smartkem Announces Preliminary Joint Development Agreement with Manz Asia for Advanced Computer and AI Chip Packaging Solutions

Joint Development Agreement builds on ongoing collaboration with Manz Asia

Manchester, England – Wednesday, July 9, 2025 – Smartkem (Nasdaq: SMTK), which is seeking to change the world of electronics with a new class of transistor technology, today announced that it has entered into a preliminary Joint Development Agreement (JDA) with Manz Asia, a pioneer in advanced packaging equipment for the semiconductor industry, which, when finalized will focus on the co-development of next generation dielectric ink solutions for advanced packaging manufacturing, particularly tailored for AI chip packaging applications.

Smartkem Chairman and CEO, Ian Jenks, comments: “This joint development agreement builds on our collaboration with Manz Asia which has already resulted in our first demonstration at SEMICON® SEA 2025 of an advanced inkjet metalization process for packaging chips for production. Together, we intend to develop scalable, high-performance solutions that address the critical bottlenecks particularly in advanced computer and AI chip packaging. By combining Smartkem’s unique semiconductor materials with Manz’s precision inkjet technology, we expect to create new manufacturing paradigms that address the demand for 12” wafer-level packaging solutions as well as extend beyond wafer-based limitations to open the door to efficient, large-area panel packaging. If successful our efforts will result in higher yield and lower cost per packaged chip, which we believe is critical for data centers deploying tens of thousands of AI accelerators.”

Manz Asia General Manager, Robert Lin, comments, “By combining Smartkem’s expertise in material science with Manz Asia’s engineering excellence in semiconductor manufacturing equipment, we believe that this JDA will fast-track the industrial adoption of dielectric ink technology, delivering new levels of scalability, resolution, and reliability for future chip integration. Dielectric inks play a critical role in back-end-of-line (BEOL) processes, particularly in top metal layer insulation and redistribution layer (RDL) patterning for advanced packaging. Smartkem’s innovative dielectric formulations offer high-resolution patterning, robust film integrity, and excellent chemical compatibility – essential for supporting today’s complex interconnect architectures.”

As demand for AI computing accelerates, advances in 12” wafer-level packaging and large-area panel packaging could offer a transformative path forward for data center infrastructure. By moving beyond the limitations of traditional wafer-based approaches, panel-level packaging enables higher chip density, faster interconnects, improved thermal management, and more sustainable manufacturing processes. Smartkem and Manz believe that these benefits are essential to scaling the next generation of AI hardware, delivering greater performance and efficiency while reducing cost and environmental impact.

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PRESS RELEASE

The JDA is preliminary only, is not-binding on the parties and there can be no assurance as to whether or when a definitive development agreement will be executed by the parties or as to the ultimate terms or outcome of any such project.

About Smartkem

Smartkem is seeking to change the world of electronics with a new class of transistors developed using its proprietary advanced semiconductor materials. Our TRUFLEX® semiconductor polymers enable low temperature printing processes that are compatible with existing manufacturing infrastructure to deliver low-cost, high-performance displays. Our semiconductor platform can be used in a range of display technologies including MicroLED, LCD and AMOLED, as well as in applications in advanced computer and AI chip packaging, sensors, and logic.

Smartkem designs and develops its materials at its research and development facility in Manchester, UK and provides prototyping services at the Centre for Process Innovation (CPI) in Sedgefield, UK. It operates a field application office in Hsinchu, Taiwan, close to collaboration partner, The Industrial Technology Research Institute (ITRI). Smartkem is developing a commercial-scale production process and Electronic Design Automation (EDA) tools to demonstrate the commercial viability of manufacturing a new generation of displays using its materials.

The company has an extensive IP portfolio including 140 granted patents across 17 patent families, 14 pending patents and 40 codified trade secrets.

For more information, visit our [website](#) or follow us on [LinkedIn](#).

About Manz Asia

Manz Asia is a leading manufacturer of advanced semiconductor equipment, driving technological innovation and process excellence within the CoPoS (CoWoS panelization) technology framework for panel-level packaging.

We offer comprehensive equipment solutions encompassing wet chemistry, plating, digital printing, automation, and proprietary software integration for Redistribution Layer (RDL) process—from lab-scale to mass production. Our technologies support key applications in Fan-Out Panel-Level Packaging (FOPLP), Through Glass Via (TGV), and IC substrates, covering critical stages of semiconductor packaging.

By enhancing production efficiency, optimizing process quality, and strengthening market competitiveness, Manz Asia empowers the semiconductor industry to achieve higher standards of excellence.

For more information, please visit [website](#) or follow us on [LinkedIn](#).

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Smartkem

PRESS RELEASE

Forward-Looking Statements

All statements in this press release that are not historical are forward-looking statements, including, among other things, its market position and market opportunity, expectations and plans as to its product development, manufacturing and sales, and relations with its partners and investors. These statements are not historical facts but rather are based on Smartkem, Inc.'s current expectations, estimates, and projections regarding its business, operations and other similar or related factors. Words such as "may," "will," "could," "would," "should," "anticipate," "predict," "potential," "continue," "expect," "intend," "plan," "project," "believe," "estimate," and other similar or related expressions are used to identify these forward-looking statements, although not all forward-looking statements contain these words. You should not place undue reliance on forward-looking statements because they involve known and unknown risks, uncertainties, and assumptions that are difficult or impossible to predict and, in some cases, beyond the Company's control. Actual results may differ materially from those in the forward-looking statements as a result of a number of factors, including those described in the Company's filings with the Securities and Exchange Commission. The Company undertakes no obligation to revise or update information in this release to reflect events or circumstances in the future, even if new information becomes available.

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